

OSG65R099xF_Datasheet



Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Low $R_{DS(on)}$ & FOM
- ◆ Excellent low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Applications

- ◆ PC power
- ◆ Server power supply
- ◆ Telecom
- ◆ Solar invertor
- ◆ Super charger for automobiles

■ General Description

OSG65R099xF use advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for telecom and super charger applications.

◆ V_{DS} , min@ T_{jmax}	700 V
◆ I_D , pulse	120 A
◆ $R_{DS(ON)}$, max @ $V_{GS}=10$ V	99 mΩ
◆ Q_g	43.6 nC

■ Schematic and Package Information



■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	650	V
Gate source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	40	A
Continuous drain current ¹⁾ , $T_C=100^\circ\text{C}$		25	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	I_D , pulse	120	A
Power dissipation ³⁾ for TO247, $T_C=25^\circ\text{C}$	P_D	278	W
Power dissipation ³⁾ for TO220F, $T_C=25^\circ\text{C}$		35	
Single pulsed avalanche energy ⁵⁾	E_{AS}	1000	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0...480$ V	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0...480$ V, $I_{SD} \leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg} , T_j	-55 to 150	°C

■ Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO247	TO220F	
Thermal resistance, junction-case	R _{θJC}	0.45	3.6	°C/W
Thermal resistance, junction-ambient ⁴⁾	R _{θJA}	62	62.5	°C/W

■ Electrical Characteristics at T_j=25 °C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV _{DSS}	650			V	V _{GS} =0 V, I _D =1 mA
		700	770			V _{GS} =0 V, I _D =1 mA, T _j =150 °C
Gate threshold voltage	V _{GS(th)}	3.0		4.0	V	V _{DS} =V _{GS} , I _D =1 mA
Drain-source on-state resistance	R _{DS(ON)}		0.08	0.099	Ω	V _{GS} =10 V, I _D =20 A
			0.205			V _{GS} =10 V, I _D =20 A, T _j =150 °C
Gate-source leakage current	I _{GSS}			100	nA	V _{GS} =30 V
				-100		V _{GS} =-30 V
Drain-source leakage current	I _{DSS}			1	μA	V _{DS} =650 V, V _{GS} =0 V

■ Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		3042.6		pF	V _{GS} =0 V, V _{DS} =50 V, f=200 kHz
Output capacitance	C _{oss}		200.6		pF	
Reverse transfer capacitance	C _{rss}		3.9		pF	
Turn-on delay time	t _{d(on)}		68.1		ns	I _D =20 A, V _{GS} =10 V, V _{DS} =400 V, R _G =25 Ω,
Rise time	t _r		53.7		ns	
Turn-off delay time	t _{d(off)}		109.6		ns	
Fall time	t _f		56.4		ns	

■ Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		43.6		nC	$I_D=20\text{ A}$, $V_{DS}=400\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		13		nC	
Gate-drain charge	Q_{gd}		13.4		nC	
Gate plateau voltage	$V_{plateau}$		5.6		V	

■ Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward current	I_S			40	A	$V_{GS} < V_{th}$
Pulsed source current	I_{SP}			120		
Diode forward voltage	V_{SD}			1.4	V	$I_S=40\text{ A}, V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		441.5		ns	$I_S=20\text{ A},$ $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		7.5		μC	
Peak reverse recovery current	I_{rrm}		31.2		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^{\circ}\text{C}$.
- 5) $V_{DD}=100\text{ V}$, $R_G=25\text{ }\Omega$, $L=20\text{ mH}$, starting $T_j=25\text{ }^{\circ}\text{C}$.

■ Electrical Characteristics Diagrams

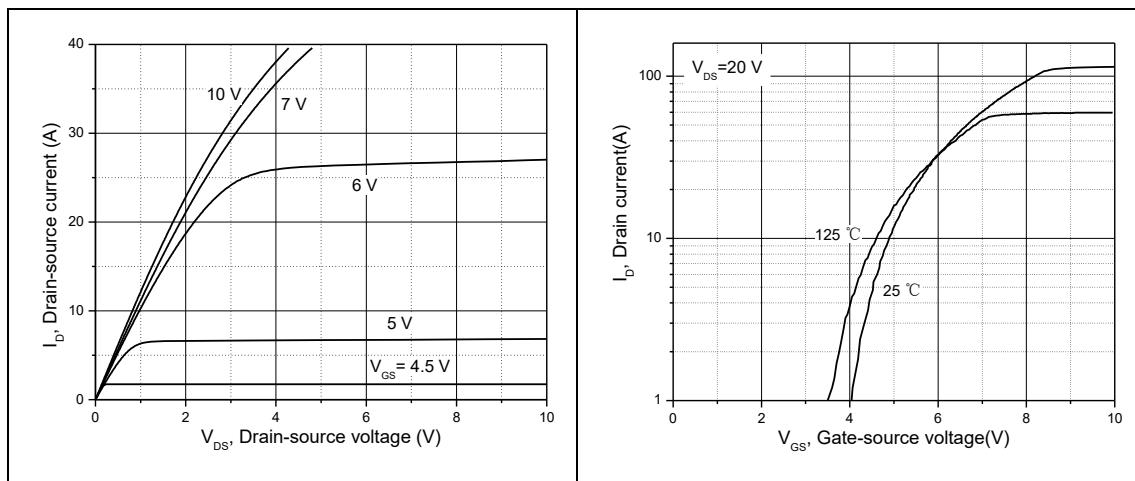


Figure 1, Typ. output characteristics

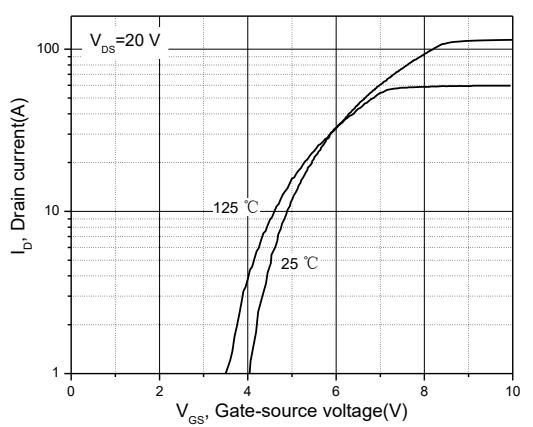


Figure 2, Typ. transfer characteristics

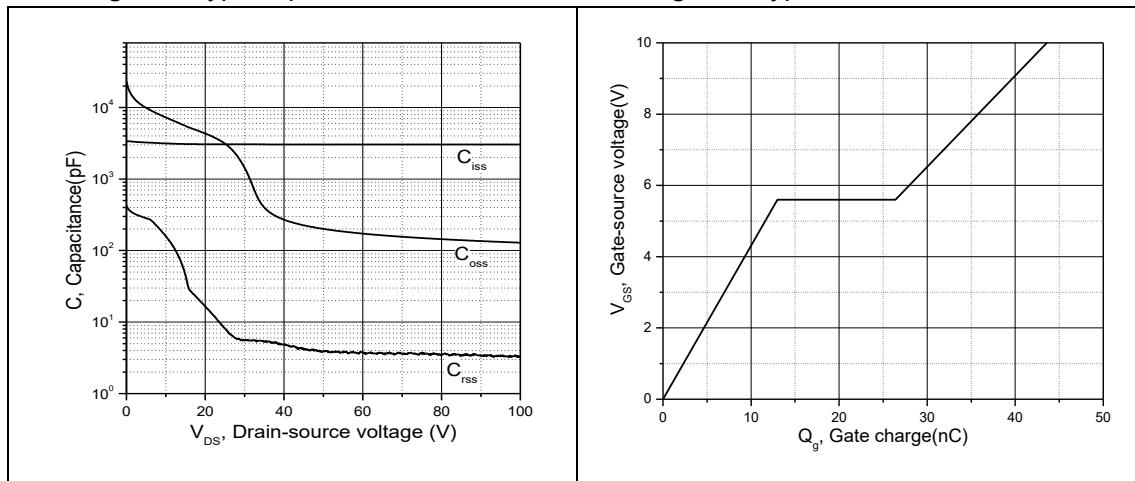


Figure 3, Typ. capacitances

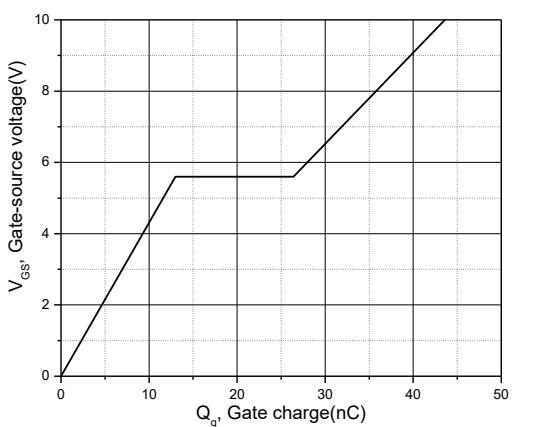


Figure 4, Typ. gate charge

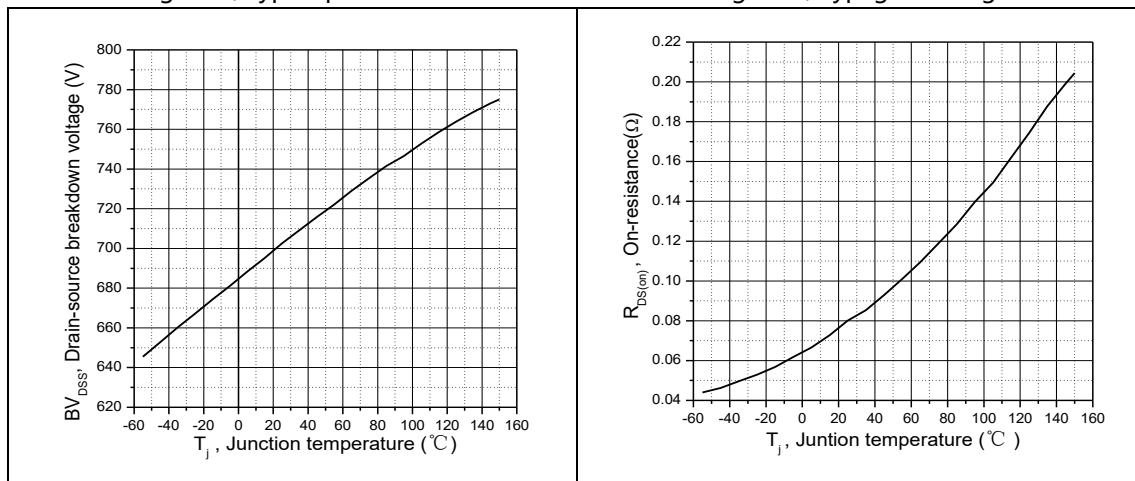


Figure 5, Drain-source breakdown voltage

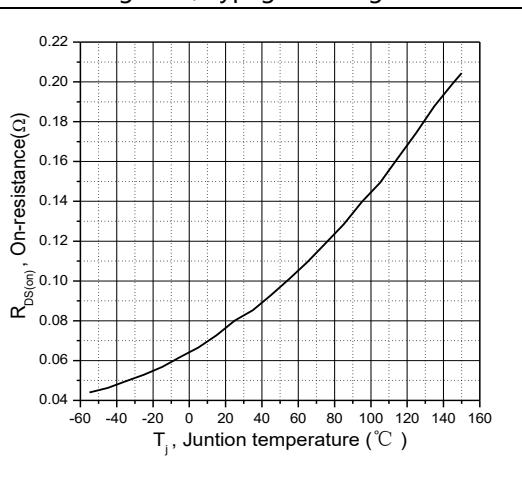


Figure 6, Drain-source on-state resistance

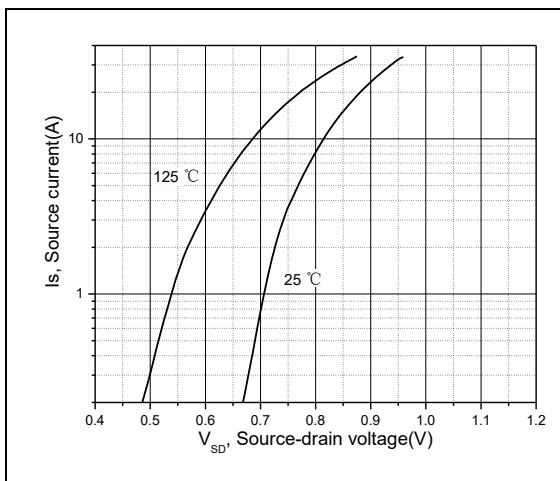


Figure 7, Forward characteristic of body diode

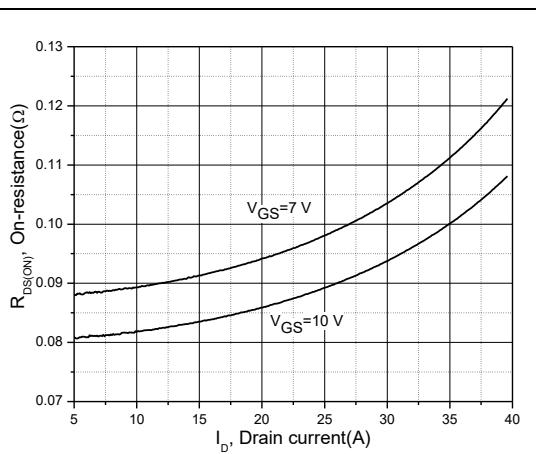


Figure 8, Drain-source on-state resistance

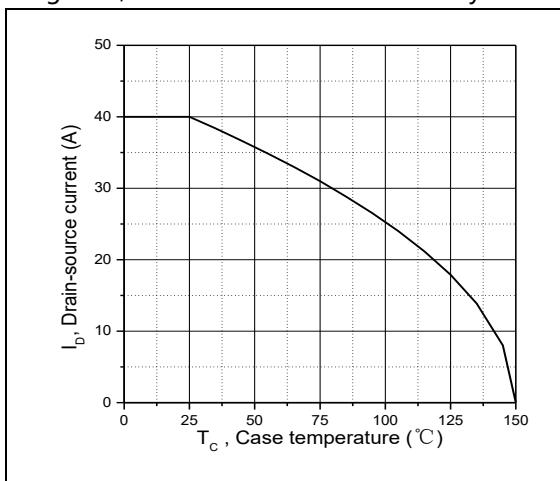


Figure 9, Drain current

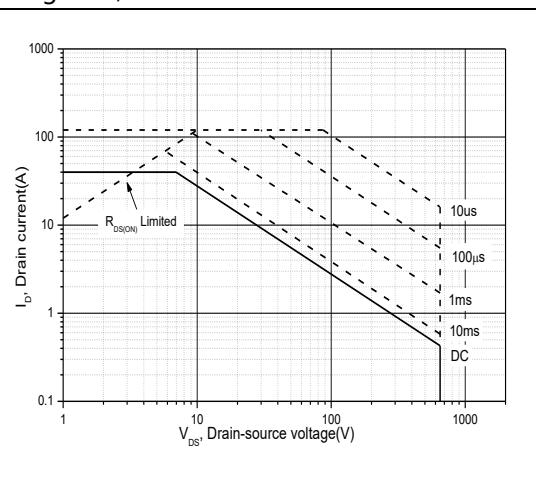


Figure 10, Safe operation area for TO247
 $T_C=25\text{ }^{\circ}\text{C}$

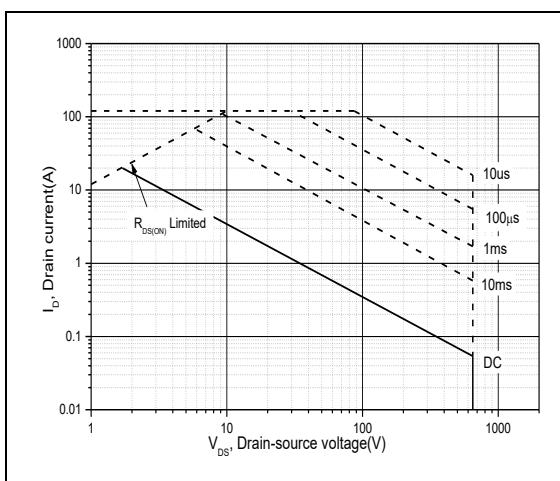


Figure 11, Safe operation area for TO220F
 $T_C=25\text{ }^{\circ}\text{C}$

■ Test circuits and waveforms

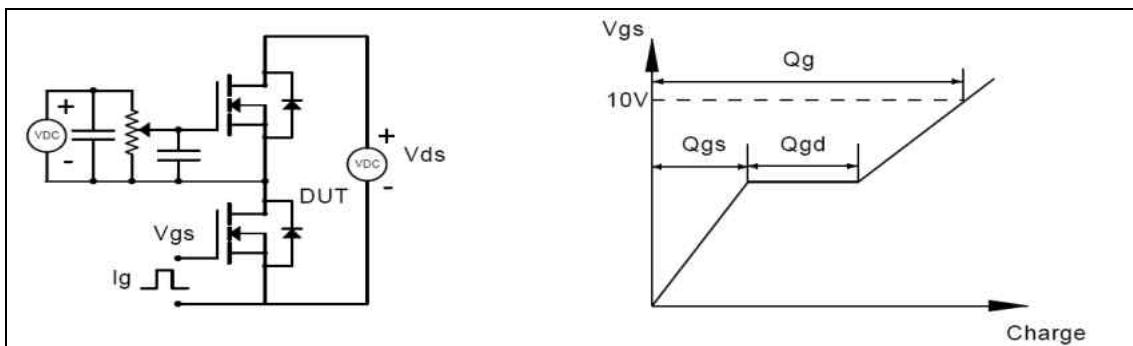


Figure 1, Gate charge test circuit & waveform

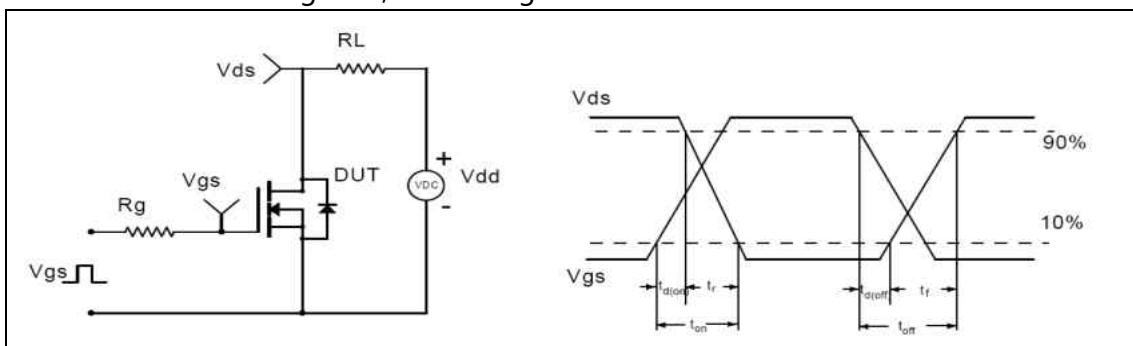


Figure 2, Switching time test circuit & waveforms

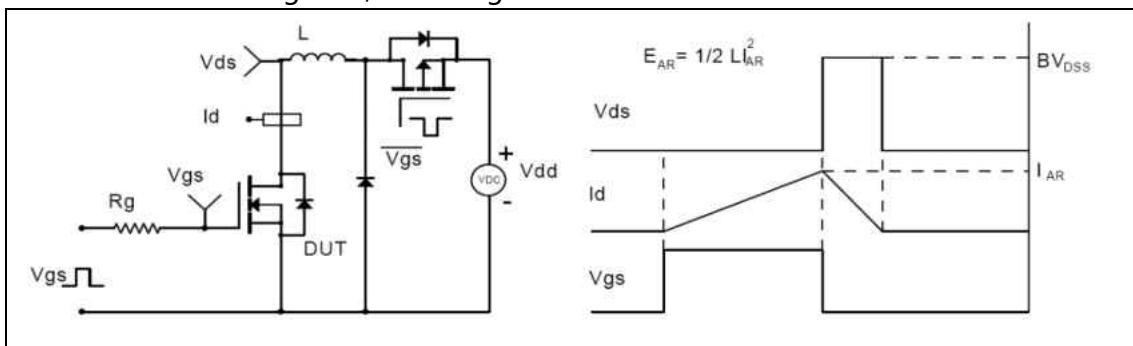


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

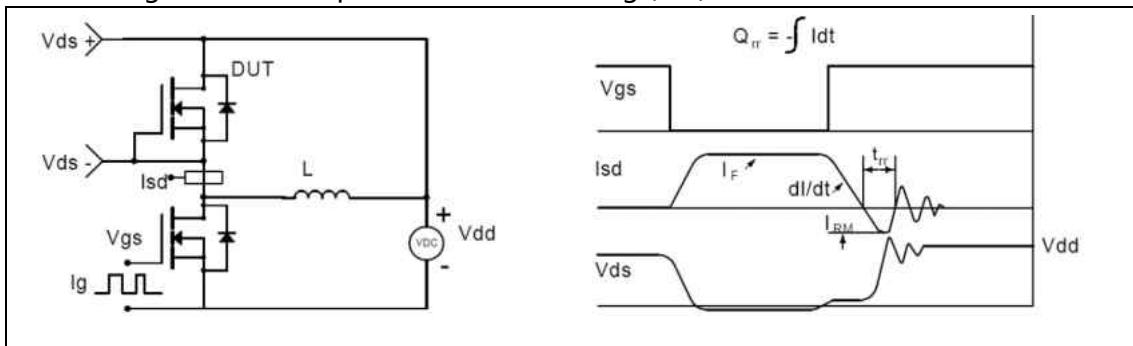
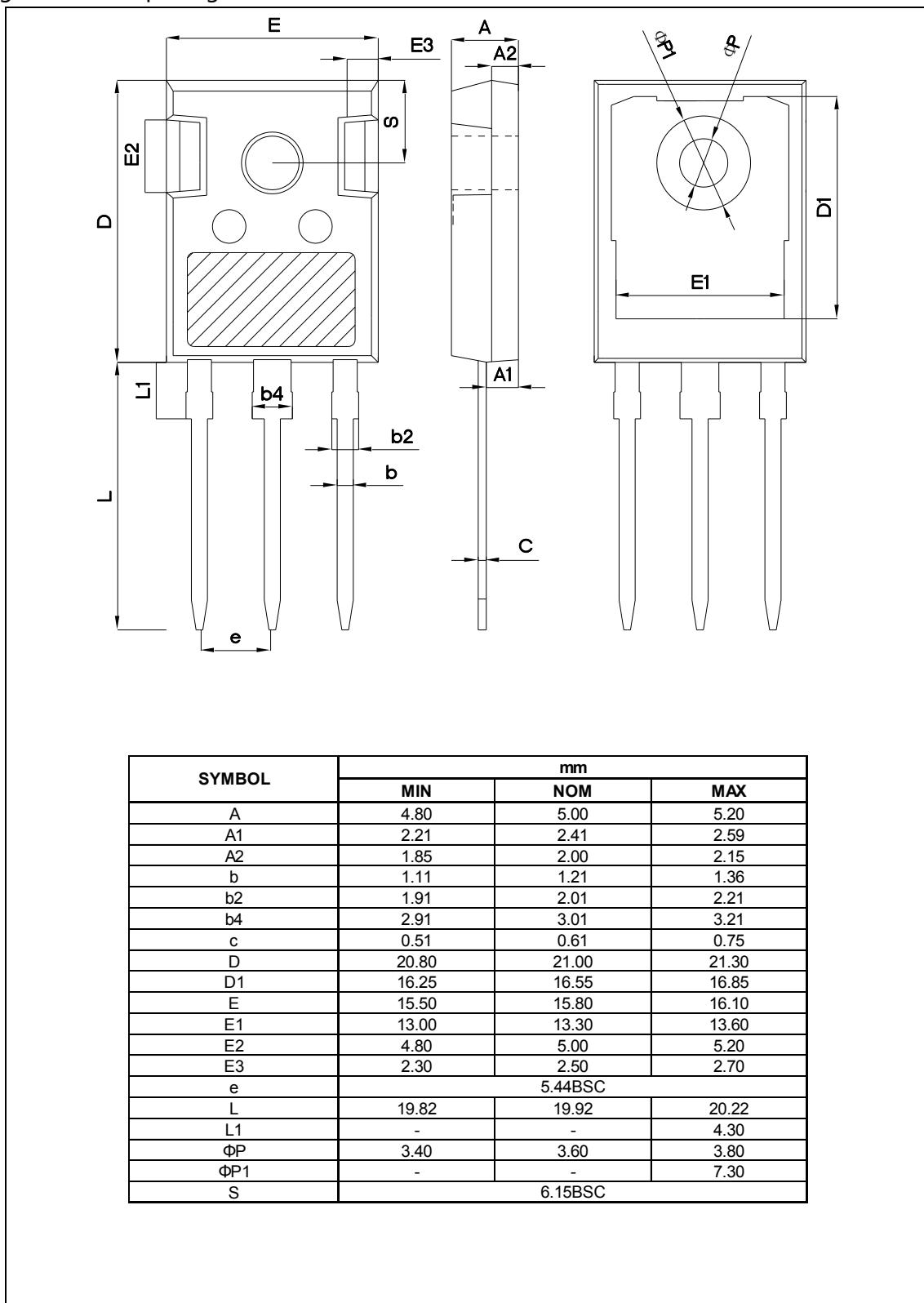


Figure 4, Diode reverse recovery test circuit & waveforms

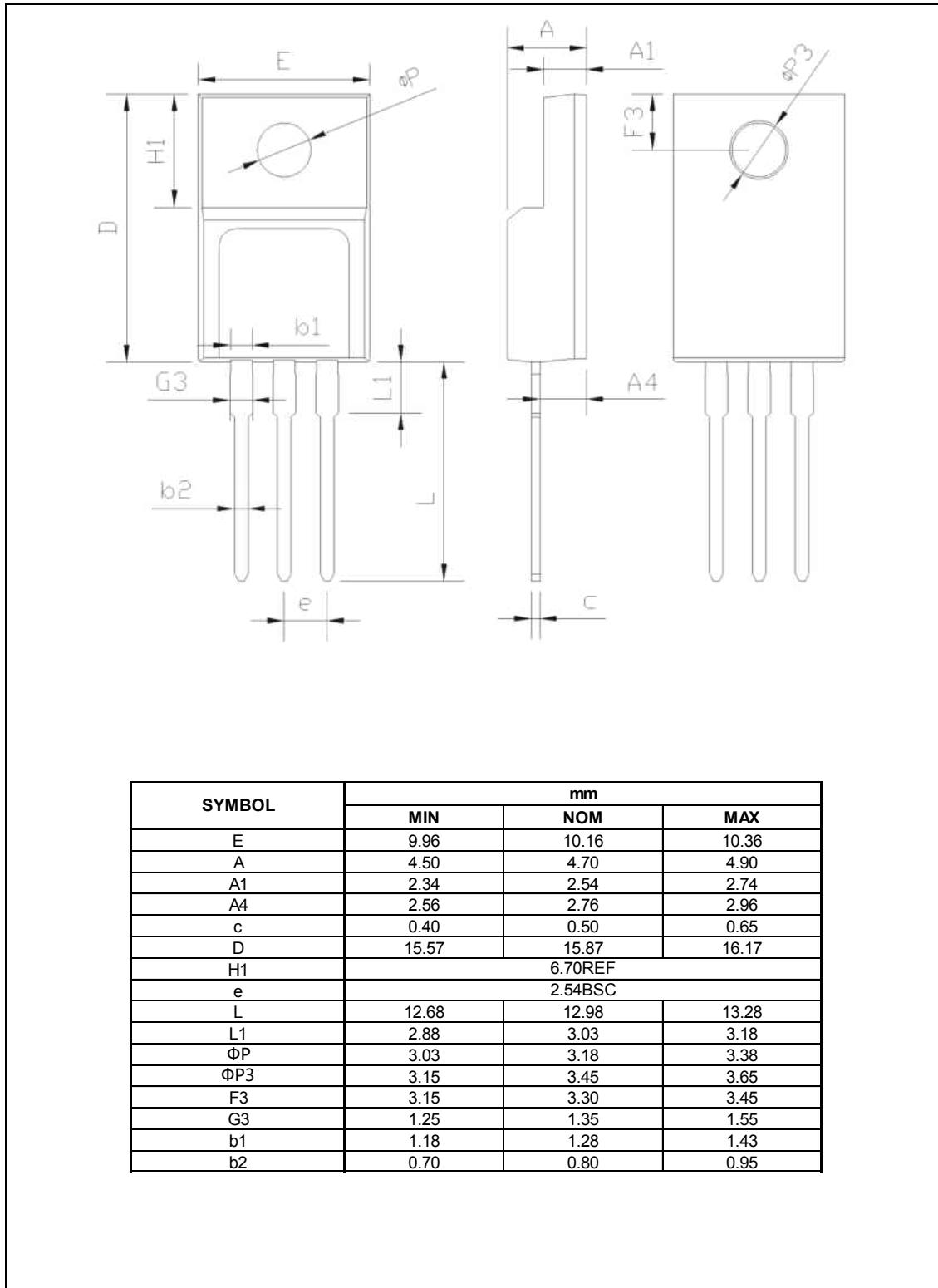
■ Package Information

Figure1, TO247 package outline dimension



■ Package Information

Figure2, TO220F package outline dimension



■ Ordering Information

Package	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO220F	50	20	1000	6	6000
TO247	30	11	330	6	1980

■ Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R099FF	TO220F	yes	yes	yes
OSG65R099HF	TO247	yes	yes	yes